

Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)} \text{ max}$	$I_D \text{ max}$ $T_A = +25^\circ\text{C}$
-60V	50mΩ @ $V_{GS} = -10\text{V}$	-4.8A
	70mΩ @ $V_{GS} = -4.5\text{V}$	-4.1A

Features and Benefits

- Low $R_{DS(ON)}$ – Ensures On State Losses Are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies Just 33% of The Board Area Occupied by SO-8 Enabling Smaller End Product
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Description and Applications

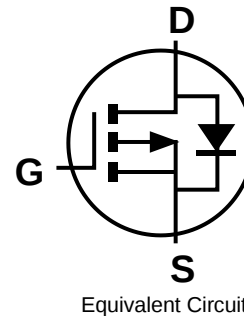
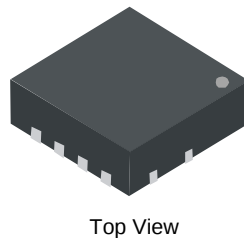
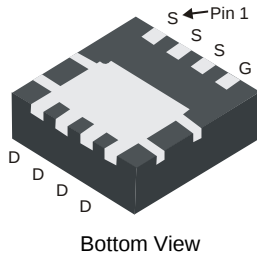
This MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

Mechanical Data

- Case: POWERDI®3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish — Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 Ⓔ3
- Weight: 0.072 grams (Approximate)

POWERDI®3333-8

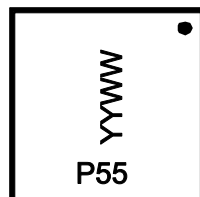


Ordering Information (Note 4)

Part Number	Case	Packaging
DMP6050SFG-7	POWERDI®3333-8	2000/Tape & Reel
DMP6050SFG-13	POWERDI®3333-8	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



P55= Product Type Marking Code
YYWW = Date Code Marking
YY = Last Digit of Year (ex: 14 = 2014)
WW = Week Code (01 to 53)

Maximum Ratings @T_A = +25°C, unless otherwise specified.

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	-60	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 6) V _{GS} = -10V	Steady State	T _A = +25°C T _A = +70°C	I _D	-4.8 -3.9	A
	t < 10s	T _A = +25°C T _A = +70°C	I _D	-6.0 -4.8	A
Pulsed Drain Current (10μs pulse, duty cycle = 1%)			I _{DM}	-32	A
Maximum Continuous Body Diode Forward Current (Note 6)			I _S	-2.8	A
Avalanche Current (Note 7) L = 0.1mH			I _{AS}	-24.8	A
Repetitive Avalanche Energy (Note 7) L = 0.1mH			E _{AS}	30.8	mJ

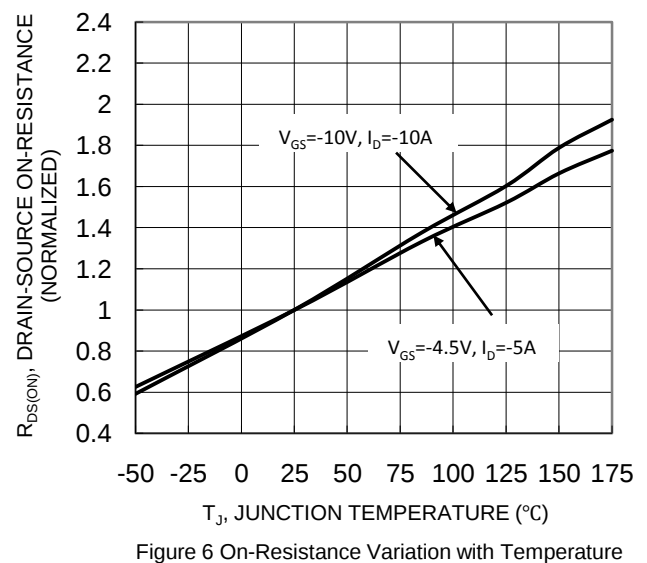
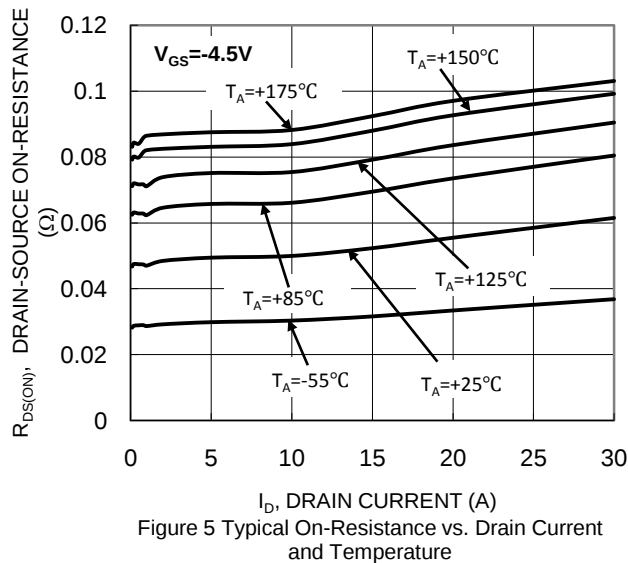
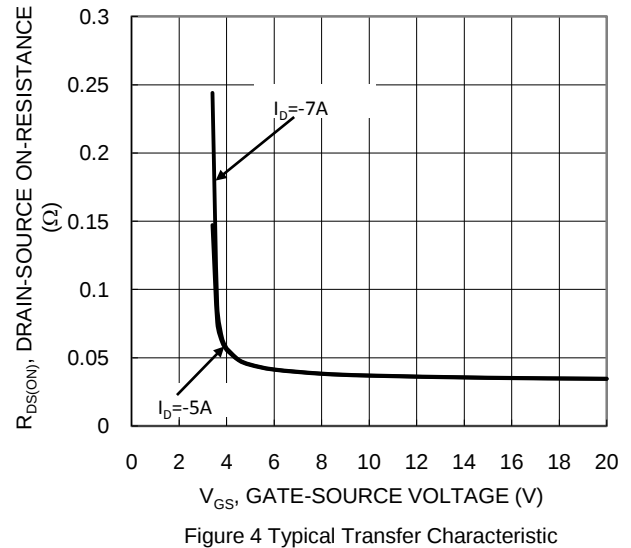
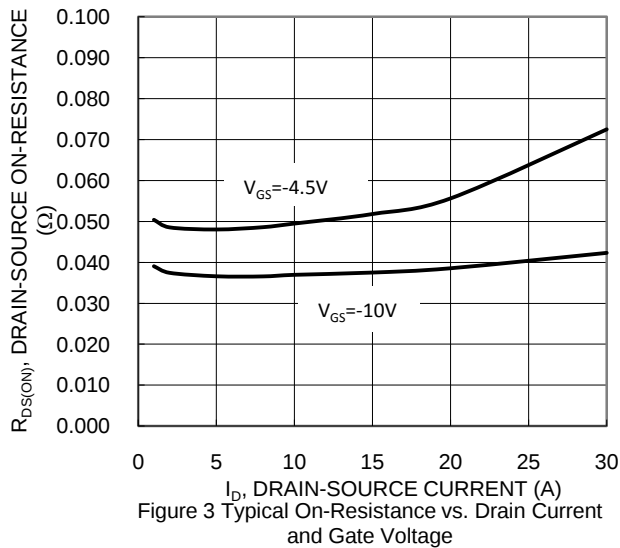
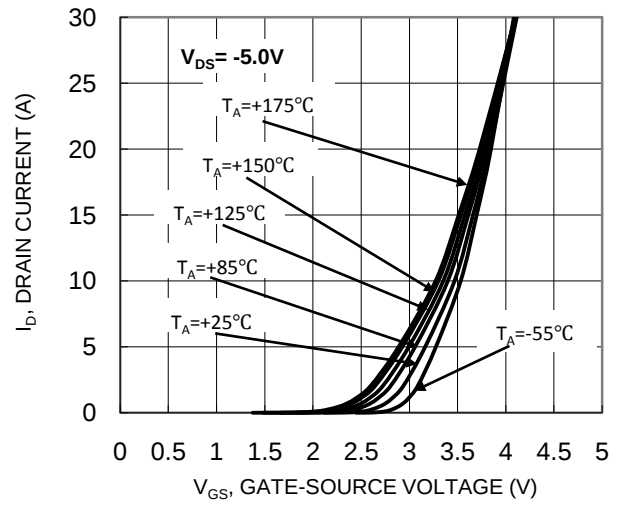
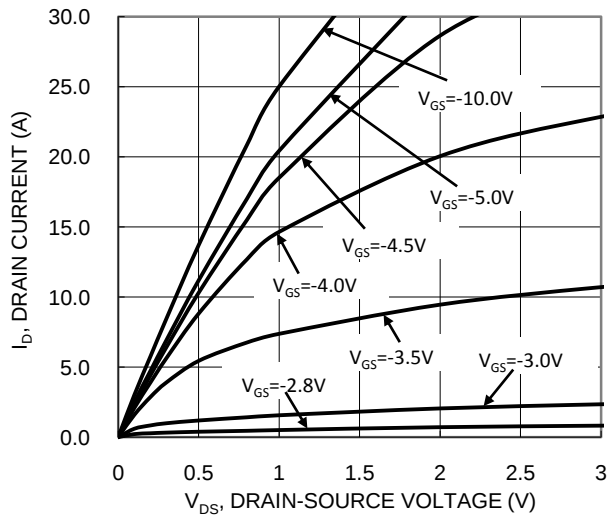
Thermal Characteristics @T_A = +25°C, unless otherwise specified.

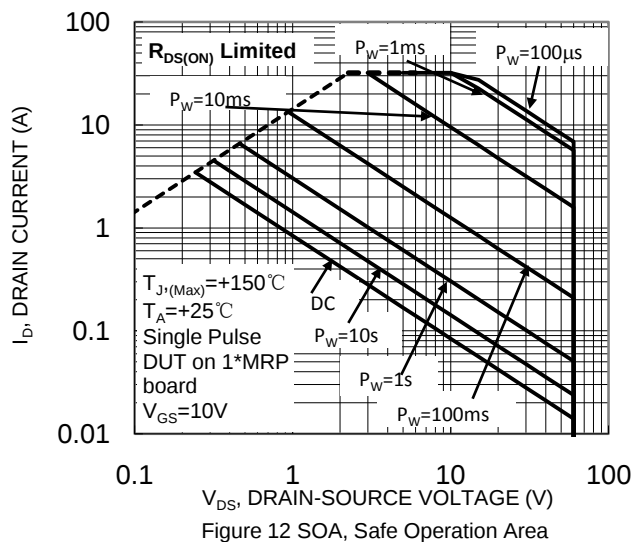
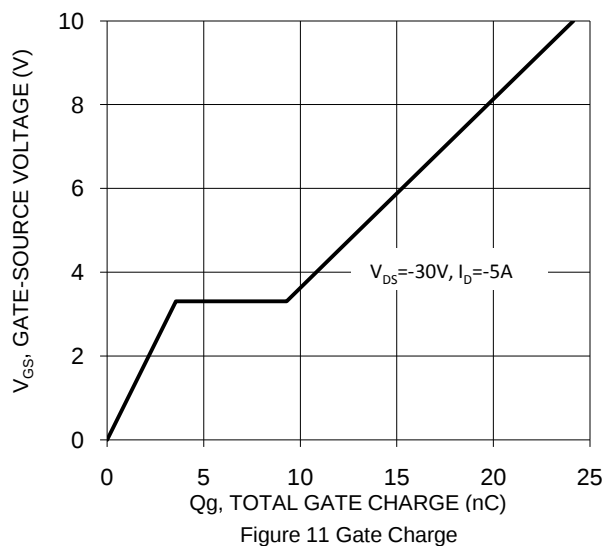
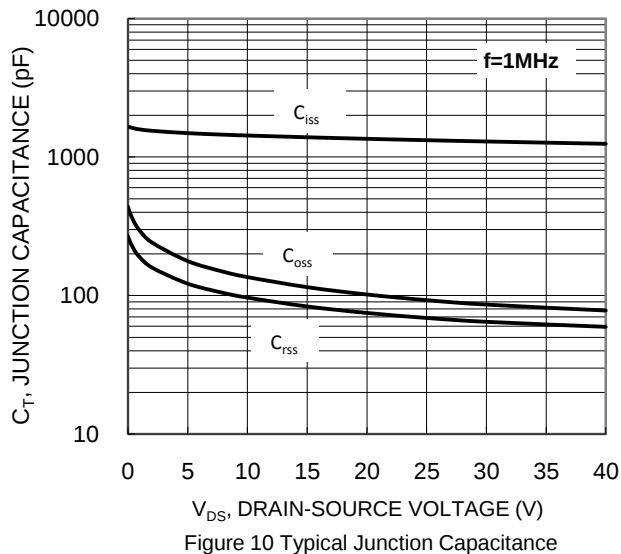
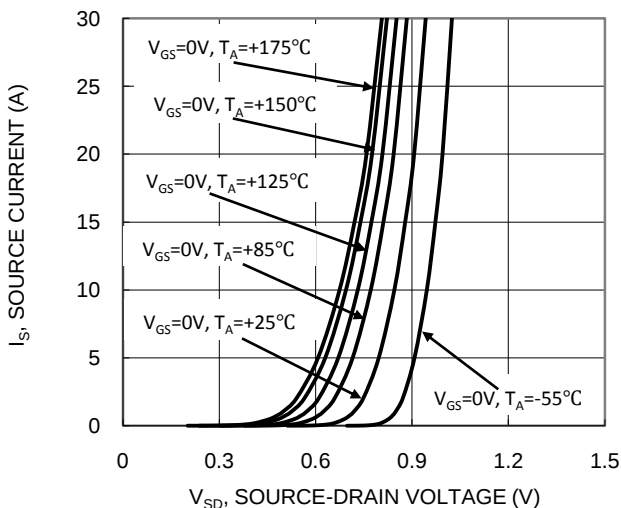
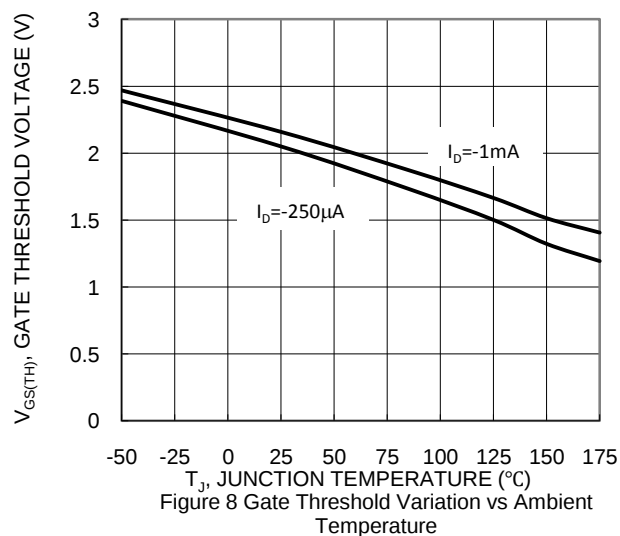
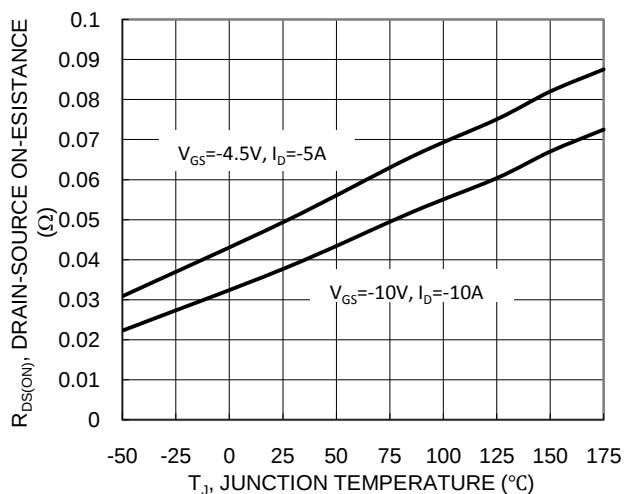
Characteristic			Symbol	Value	Unit
Total Power Dissipation (Note 5)			P _D	1.1	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady state		R _{θJA}	118	°C/W
	t < 10s			78	
Total Power Dissipation (Note 6)			P _D	1.8	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state		R _{θJA}	71	°C/W
	t < 10s			46	
Thermal Resistance, Junction to Case (Note 6)			R _{θJC}	6.7	
Operating and Storage Temperature Range			T _J , T _{STG}	-55 to +150	°C

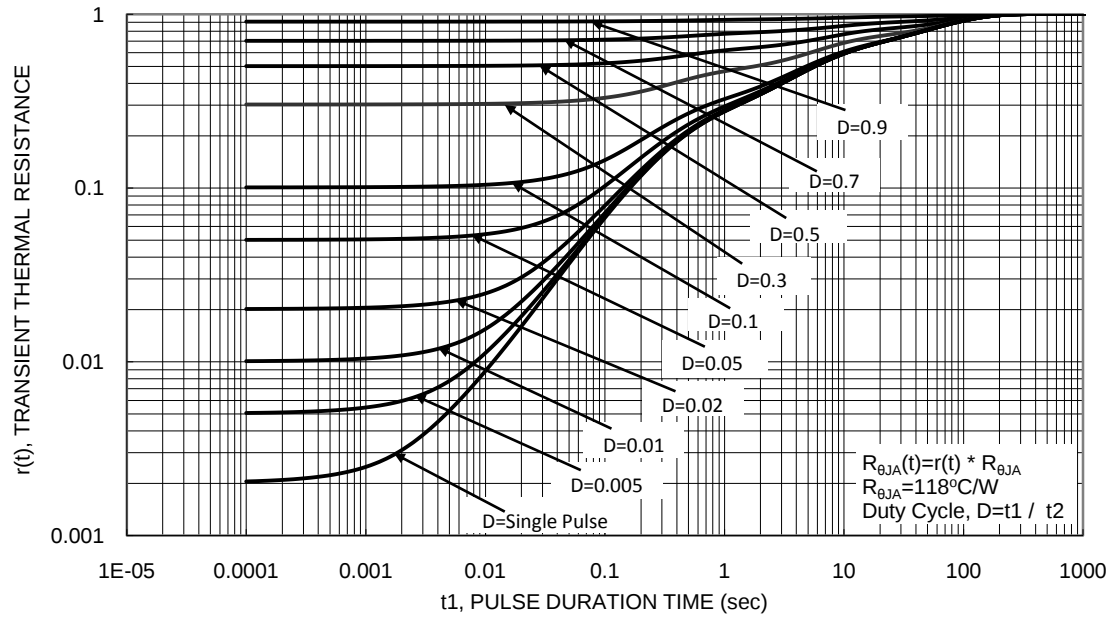
Electrical Characteristics @T_A = +25°C, unless otherwise specified.

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV _{DSS}	-60	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	—	—	-1	μA	V _{DS} = -60V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V _{GS(TH)}	-1.0	—	-3.0	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	36	50	mΩ	V _{GS} = -10V, I _D = -5A
		—	47	70		V _{GS} = -4.5V, I _D = -4A
Diode Forward Voltage	V _{SD}	—	-0.7	-1.2	V	V _{GS} = 0V, I _S = -1A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C _{iss}	—	1293	—	pF	V _{DS} = -30V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{oss}	—	86.3	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	64.7	—	pF	
Gate Resistance	R _g	—	12	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz
Total Gate Charge (V _{GS} = -4.5V)	Q _g	—	11.9	—	nC	V _{DS} = -30V, I _D = -5A
Total Gate Charge (V _{GS} = -10V)	Q _g	—	24	—	nC	
Gate-Source Charge	Q _{gs}	—	3.6	—	nC	
Gate-Drain Charge	Q _{gd}	—	5.7	—	nC	
Turn-On Delay Time	t _{D(ON)}	—	4.3	—	ns	V _{GS} = -10V, V _{DS} = -30V, R _G = 3Ω, I _D = -5A
Turn-On Rise Time	t _R	—	6.3	—	ns	
Turn-Off Delay Time	t _{D(OFF)}	—	46.7	—	ns	
Turn-Off Fall Time	t _F	—	25.3	—	ns	
Body Diode Reverse Recovery Time	t _{RR}	—	13.6	—	ns	I _F = -5A, di/dt = 100A/μs
Body Diode Reverse Recovery Charge	Q _{RR}	—	7.4	—	nC	I _F = -5A, di/dt = 100A/μs

- Notes:
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 - I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.

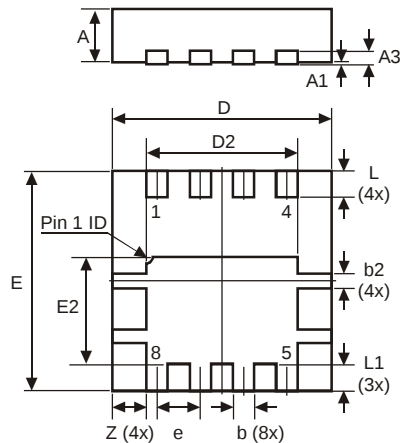






Package Outline Dimensions

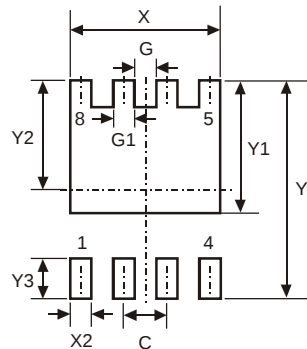
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



POWERDI [®] 3333-8			
Dim	Min	Max	Typ
D	3.25	3.35	3.30
E	3.25	3.35	3.30
D2	2.22	2.32	2.27
E2	1.56	1.66	1.61
A	0.75	0.85	0.80
A1	0	0.05	0.02
A3	—	—	0.203
b	0.27	0.37	0.32
b2	—	—	0.20
L	0.35	0.45	0.40
L1	—	—	0.39
e	—	—	0.65
Z	—	—	0.515
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	0.650
G	0.230
G1	0.420
Y	3.700
Y1	2.250
Y2	1.850
Y3	0.700
X	2.370
X2	0.420

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